



General Description

The WSR2N65 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSR2N65 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

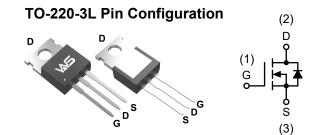
- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

BV _{DSS}	R _{DSON}	I _D
650V	4000mΩ	2A

Applications

- AC/DC Power Conversion in Switched Mode Power Supplies (SMPS).
- Uninterruptible Power Supply(UPS)
- Adapter.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	±30	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ^{1.5}	2	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ^{1.5}	1	А
I _{DM}	Pulsed Drain Current ^{1.2.5}	6	A
EAS	Single Pulse Avalanche Energy ¹	57	mJ
P _D	Total Power Dissipation ^{1,5}	25	W
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$ C
T _J	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-ambient ¹		62.5	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		5	°C/W



Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	650			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I _D =250uA		0.6		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V_{GS} =10V , I_D =1A		4000	4800	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} . In =250uA	2.0	3.0	4.0	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS, ID -230UA		-4.57		mV/℃
less	Drain-Source Leakage Current	V_{DS} =650V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	uA
I _{DSS}	Diani-Source Leakage Current	V_{DS} =520V , V_{GS} =0V , T_J =55 $^{\circ}$ C			10	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm30V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =300V , I _D =1A		5		S
Q_g	Total Gate Charge (10V)			8.0		
Q _{gs}	Gate-Source Charge V_{DS} =520V , V_{GS} =10V , I_{D} =1A			1.2		nC
Q_gd	Gate-Drain Charge			5		
T _{d(on)}	Turn-On Delay Time			7.8		
T _r	Rise Time	V _{DD} =300V , V _{GS} =10V ,		33		no
T _{d(off)}	Turn-Off Delay Time	$R_G=25\Omega$, $I_D=1A$.		23		ns
T _f	Fall Time			59		
C _{iss}	Input Capacitance			310		
Coss	Output Capacitance	V _{DS} =25V , V _{GS} =0V , f=1MHz		39		pF
C _{rss}	Reverse Transfer Capacitance			6		

Diode Characteristics

Symbol	Parameter	Conditions		Тур.	Max.	Unit
Is	Continuous Source Current ^{1,2,5}	V =V =0V Force Current			2	Α
I _{SM}	Pulsed Source Current ^{1,2}	V _G =V _D =0V , Force Current			6	Α
V _{SD}	Diode Forward Voltage ¹	V _{GS} =0V , I _S =2A , T _J =25℃			1.4	V
t _{rr}	Reverse Recovery Time			80		nS
Q _{rr}	Reverse Recovery Charge	lF=2A , dl/dt=100A/μs		1800		nC

Notes:

Note 1 : limited by maximum junction temperature.

Note 2: Bond wire current limit. Note 3: V_{DS}=520V, I_D=2A.

Note 4 : $I_D=1A$, $V_{DD}=50V$, $T_i=25$ °C.

Note 5: Repetitive Rating : Pulse width limited by maximum junction temperature.



Typical Characteristics

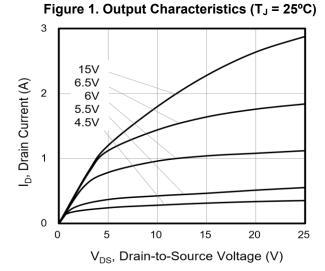


Figure 3. Drain Current vs. Temperature

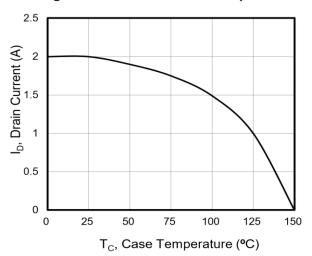


Figure 5. Transfer Characteristics

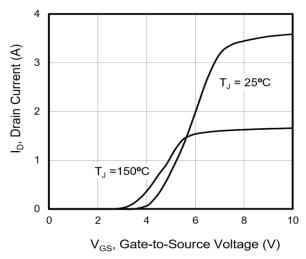
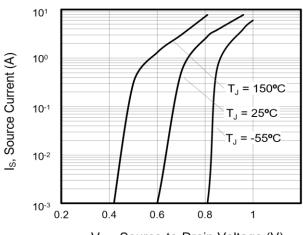


Figure 2. Body Diode Forward Voltage



V_{SD}, Source-to-Drain Voltage (V)

Figure 4. Power Dissipation vs. Temperature TO-251,TO-252

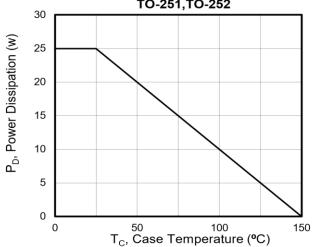
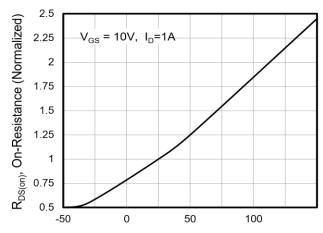


Figure 6. On-Resistance vs. Temperature

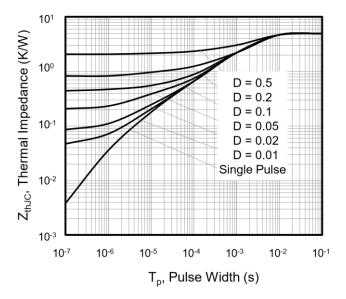


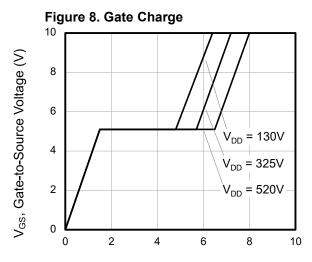
T_J, Junction Temperature (°C)



Typical Characteristics

 $V_{\text{DS}},$ Drain-to-Source Voltage (V) Figure 9. Transient Thermal Impedance

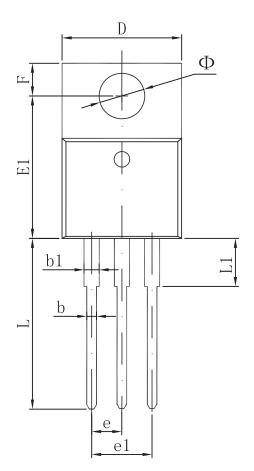


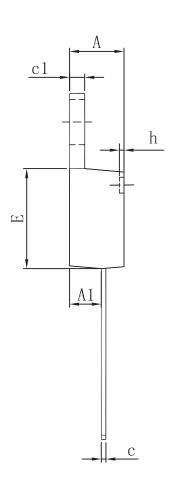


Q_g, Total Gate Charge (nC)



Packaging information





Cumbal	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
Е	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
е	2.540	O TYP	0.100) TYP
e1	4. 980	5. 180	0.196	0.204
F	2.590	2.890	0.102	0.114
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
Ф	3. 735	3. 935	0.147	0.155



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